# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

- HP Pavilion 23 All-in-One PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

**1.1 Items listed below are classified as requiring selective treatment.**

**1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.**

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MotherBoard</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.
<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>screw driver</td>
<td>TORX T8</td>
</tr>
<tr>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removed Rear Cover
2. Removed Stand base assay
3. Removed Converter board
4. Removed ODD module → Sub: remove ODD bracket
5. Removed HDD module → Sub: remove HDD cage
6. Removed MB Shielding
7. Removed Thermal module
8. Removed Fan module.
9. Removed MB
10. Removed Speaker module
11. Removed Low case module
12. Removed LCD Cover
13. Removed Front bezel
14. Removed LCD panel
15.
16.
17.
18.
19.
20.
21.
22.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

#### 3.21 Total part disassembly

![Image 1](image1.png)  
Step 1. Removed Rear Cover

![Image 2](image2.png)  
Step 2. Removed Stand base assay
Step 3. Removed Converter board

Step 4. Removed ODD module
   --> Sub: remove ODD bracket

Step 5. Removed HDD module
   --> Sub: remove HDD cage

Step 6. Removed MB Shielding

Step 7. Removed Thermal module

Step 8. Removed Fan module
Step 9. Removed MB
(RTC battery location as shown red circle).

Step 10. Removed Speaker module

Step 11. Removed Low case module

Step 12. Removed LCD cover

Step 13. Removed Front bezel

Step 14. Removed LCD panel